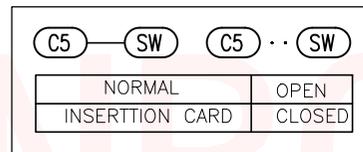
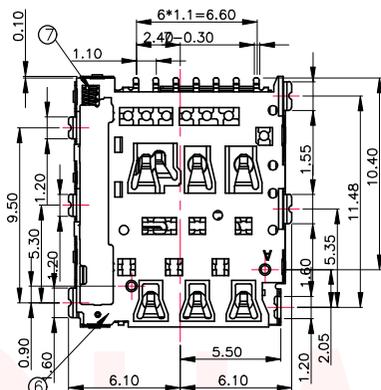
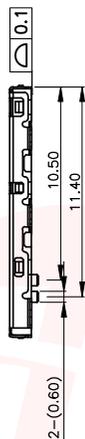
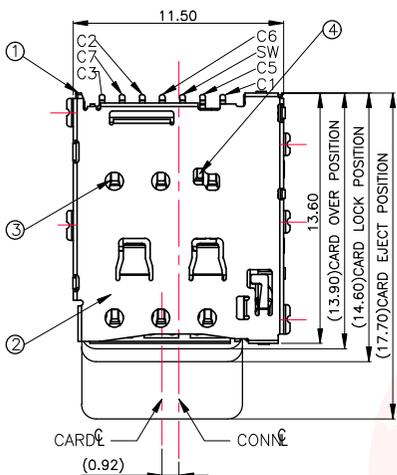
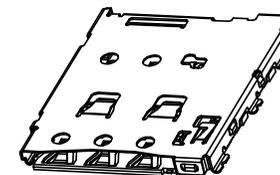
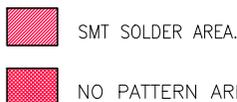
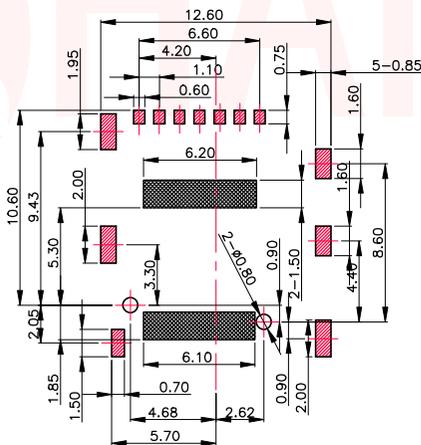
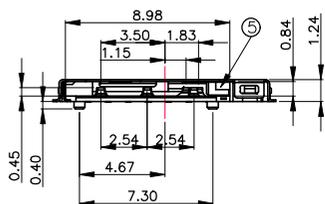




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



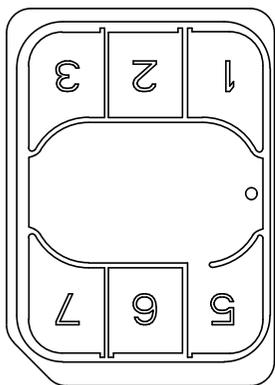
- NOTES:
- FINISH:
 - CONTACT:
 - 50 μ MIN NICKEL UNDER PLATED, 1 μ MIN GOLD PLATING ON CONTACT AREA, GOLD FLASH PLATING ON SOLDERING AREA
 - SHELL:
 - 30 μ M NICKEL UNDER PLATED;
 - 1 μ MIN GOLD PLATING ON SOLDERING AREA.
 - ELECTRICAL REQUIREMENTS:
 - RATED CURRENT: 0.5A
 - CONTACT RESISTANCE: 50m Ω MAX
 - INSULATION RESISTANCE: 1000 Ω MIN 200V DC FOR 1 MINUTE
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE.
 - MECHANICAL REQUIREMENTS:
 - DURABILITY: 3000 CYCLES MIN.
 - ENVIRONMENTAL REQUIREMENTS:
 - OPERATING TEMP: -30 $^{\circ}$ C~+85 $^{\circ}$ C
 - STORAGE TEMP: -40 $^{\circ}$ C~+85 $^{\circ}$ C
 - RECOMMENDED PROCESS CONDITION:
 - IR-REFLOW, PEAK TEMPERATURE AND TIME: 250 $^{\circ}$ C, 5-10S
 - METAL MASK THICKNESS 0.10MM MIN



RECOMMENDED PCB LAYOUT ALL TOLERANCE ± 0.05 MM

Nano SIM Circuit Description:

PIN No.	FUNCTION
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



NO.	DESCRIPTION	Q'TY	Material
7	SPRING	1	THERMOPLASTIC RATING UL94V-0
6	LINK	1	STAINLESS STEEL
5	SLIDE	1	STAINLESS STEEL
4	DETECT PIN	1	COPPER ALLOY
3	CONTACT	1	COPPER ALLOY
2	SHELL	1	STAINLESS STEEL
1	HOUSING	1	LCP UL94V-0

UNLESS OTHERWISE SPECIFIED TOLERANCES



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

DECIMALS: X ± 0.30
X.X ± 0.20
X.XX ± 0.10

ANGLES: X $\pm 2^{\circ}$
X.X $\pm 1^{\circ}$

TITLE	1.24 NANO SIM PUSH CONN CUSTOMER		
DWN	xiong	PART NO.	SNO-1420
CHKD	lee	SCALE: 1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET: 1 OF 1
			REV: A4

CUSTOMER COPY